

Sustainable Green Multicore Codesigned with Compiler



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IEEE Computer Society President 2018
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1980 BS, 82 MS, 85 Ph.D., Dept. EE, Waseda Univ.
1985 Visiting Scholar: U. of California, Berkeley,
1986 Assistant Prof., 1988 Associate Prof., 1989-90
Research Scholar: U. of Illinois, Urbana-Champaign,
Center for Supercomputing R&D, 1997 Prof.,
2004 Director, Advanced Multicore Research Institute,
2017member: the Engineering Academy of Japan
(2020- Board Mem) and the Science Council of Japan
2018 IEEE Computer Society President
Senior Executive Vice President, Waseda U. (2018-22)

AWARD: 1987 IFAC World Congress Young Author Prize
1997 IPSJ Sakai Special Research Award,
2005 STARC Academia-Industry Research Award,
2008 LSI of the Year Second Prize,
2008 Intel Asia Academic Forum Best Research Award,
2010 IEEE CS Golden Core Member Award
2014 Minister of Edu., Sci. & Tech. Research Prize
2015 IPSJ Fellow, 2017 IEEE Fellow, Eta Kappa Nu
2019 Spirit of IEEE Computer Society Award,
2020 IPSJ Contribution Award, 2023 IEEE Life Fellow

Reviewed Papers: 243, Invited Talks: 246,
Granted Patents: 72 (Japan, US, GB, DE, China),
Articles in News Papers, Web News, TV etc.: 713

Committees in Societies and Government 300
IEEE Computer Society: President 2018, Executive
Committee(2017-2019), BoG(2009-14), Strategic
Planning Committee Chair 2018, Multicore STC Chair
(2012-), Japan Chair(2005-07),
IPSJ Chair: HG for Magazine. & J. Edit, Sig. on ARC.
【METI/NEDO】Project Leaders: Multicore for
Consumer Electronics, Advanced Parallelizing Compiler,
Chair: Computer Strategy Committee [Cabinet Office]
CSTP Supercomputer Strategic ICT PT, Japan Prize
Selection Committees, etc.
【MEXT】Info. Sci. & Tech. Committee, Supercomputers
Development Member (Top 1:NWT, Earth Simulator, K)
JST SPRING Ph.D Promotion Chair, Boost AI Ph.D.
Boosting Chair, SBIR Phase 1 Chair, Moonshot Project
G3 Robot & AI Advisor & Int'l Symp Vice Chair,
【COCN】Council of Competitiveness Nippon Ex-Board

ACM/IEEE ISCA'25, Special Panel, June 22, 2025, Tokyo, Japan

Research on OSCAR Parallelizing Compiler & Co-designed Hardware Since 1984

72 international patents in USA, UK, China, Japan to improve effective
performance, cost-performance, software productivity and power efficiency

High Performance & Low Power

1) Multigrain Parallelization for Embedded to
HPC Homogeneous and Heterogeneous
Multicores

Coarse-grain task parallelism among loops,
subroutines & basic blocks in addition to
the loop parallelism

2) Data Localization:
Optimization of Cache & Local Memory Usage

> Automatic data decomposition and data
reuse control for Distributed shared memory,
Cache and Local memory

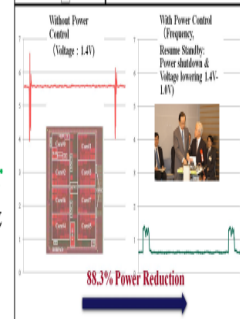
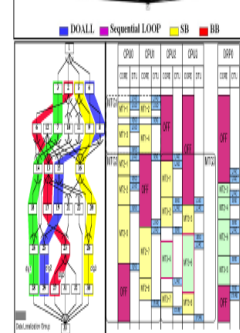
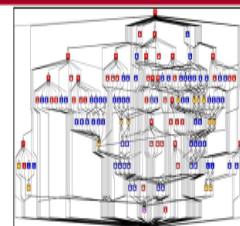
> Data Transfer Control

> Overlapping Data Transfer using Data
Transfer Unit, or DMAC

3) Automatic Power Reduction

> OSCAR Compiler can reduce power
consumption by using DVFS and Clock- &
Power-gating with hardware supports.

4) Codesigned Accelerator: See right figure

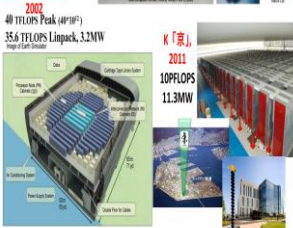


Green Accelerator

can be attached to any processor
cores, RISCv, arm, Infineon
Renesas, AMD, Intel, etc, without
instruction extensions.

> It works with automatic local
memory management and
power reduction control by
OSCAR Automatic vectorizing
& parallelizing compiler

H. Kasahara was a member of 3 World No.1 Supercomputers
"NWT: 数值風洞", "Earth Simulator: 地球シミュレータ", and "K: 京"



Demo of NEDO Green Multicore Processor for Real Time Consumer Electronics at Council of Science and Engineering Policy on April 10, 2008

<http://www8.cao.go.jp/cstp/gaiyo/honkaigi/74index.html>

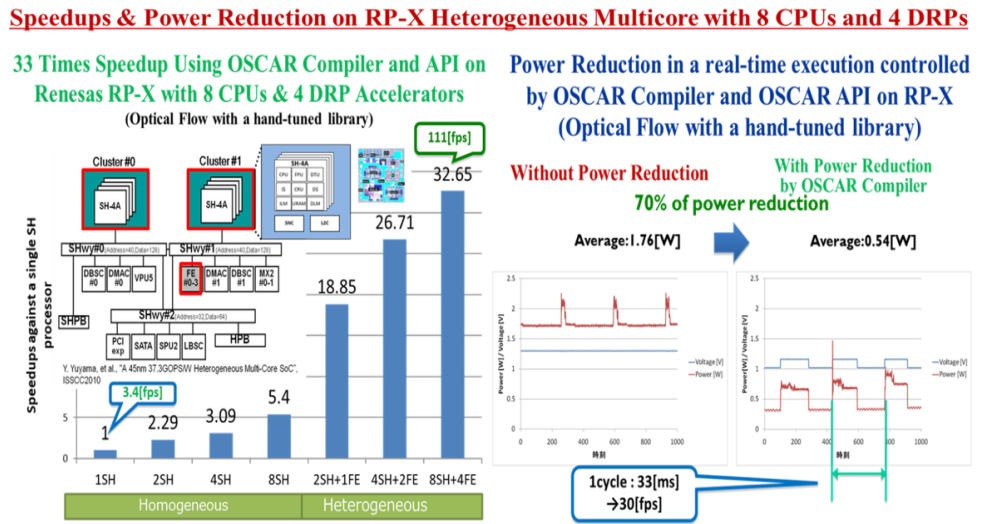
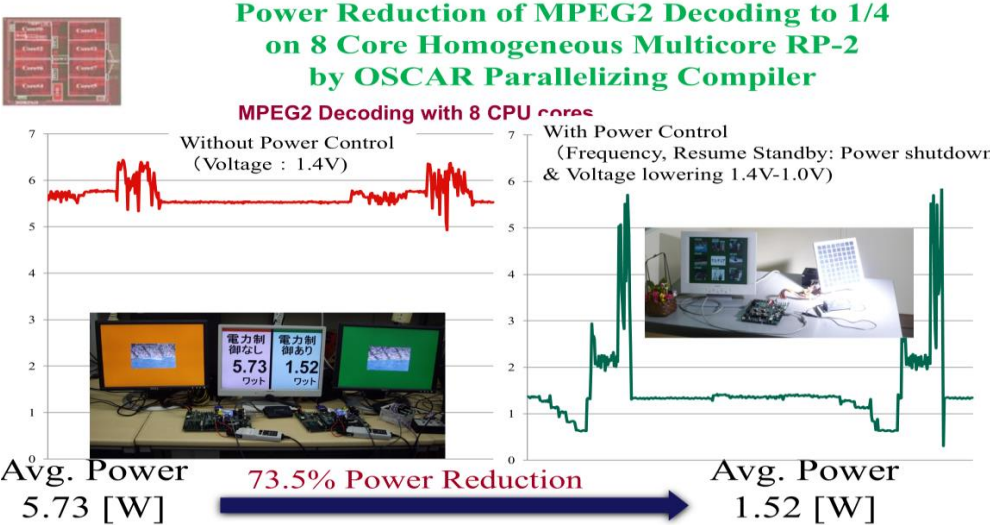


Codesign of Compiler and Multiprocessor Architecture since 1985

4 core multicore RP1 (2007), 8 core multicore RP2 (2008) and 15 core Heterogeneous multicore RPX (2010) developed in NEDO Projects with Hitachi and Renesas

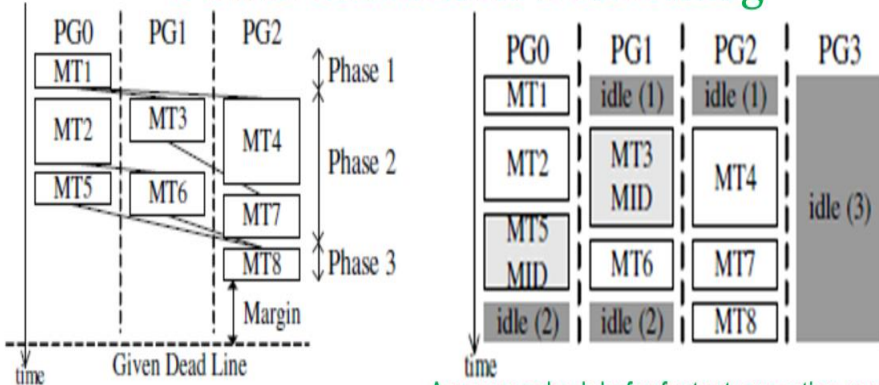
RP-1 (ISSCC2007 #5.3)	RP-2 (ISSCC2008 #4.5)	RP-X (ISSCC2010 #5.3)
90nm, 8-layer, triple-Vth, CMOS	65nm, 8-layer, triple-Vth, CMOS	45nm, 8-layer, triple-Vth, CMOS
97.6 mm ² (9.88 x 9.88 mm)	104.8 mm ² (10.61 x 9.88 mm)	153.8 mm ² (12.4 x 12.4 mm)
1.0V (internal), 1.83.3V (I/O)	1.0-1.4V (internal), 1.83.3V (I/O)	1.0-1.2V (internal), 1.2-3.3V (I/O)
600MHz, 4.32 GIPS, 16.8 GFLOPS	600MHz, 8.64 GIPS, 33.6 GFLOPS	640MHz, 13.76GIPS, 115GOPS, 36.2GFLOPS
11.4 GOPS/W (32b換算)	18.3 GOPS/W (32b換算)	37.3 GOPS/W (32b換算)

Prime Minister FUKUDA is touching our multicore chip during execution.



An Image of Static Schedule for Heterogeneous Multi-core with Data Transfer Overlapping and Power Control

Power Reduction Scheduling

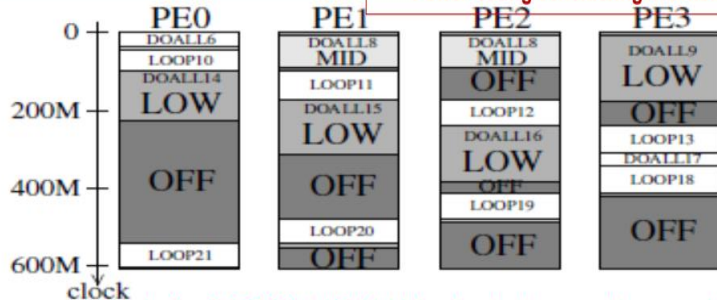


A macrotask graph assigned to 3 cores

A power schedule for fastest execution mode

Realtime scheduling mode
MTs 1,4,7,8 are on Critical Path (CP)

- 1) Reduce frequencies (F_s) of MTs on CP considering dead line.
- 2) Reduce F_s of MTs not on CP. Idle: Clock or Power Gating considering overheads.



A power schedule for SPEC95 APPLU for fastest execution mode

Doall6, Loop 10,11,12,13, Doall 17, Loop 18,19,20, 21 are on CP

